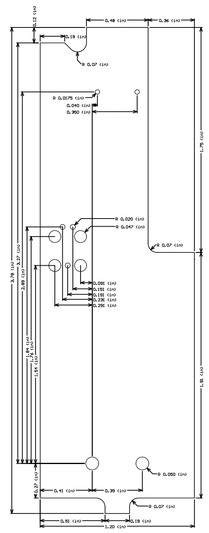
REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
C1	Release for Production	09/03/2020	M. Beach

NOTES: (UNLESS OTHERWISE SPECIFIED)

1. THIS DRAWING SPECIFIES THE REQUIREMENTS FOR A PRINTED CIRCUIT BOARD IN ACCORDANCE WITH SPECIFICATION IPC-6012 CLASS 2 (LATEST REVISION).
2. THE PCB MUST BE LEAD FREE ASSEMBLY PROCESS COMPATIBLE AND MUST BE ABLE TO HANDLE A MINIMUM OF 5 CYCLES AT 260 DEGREES CELSIUS FOR 10 SECONDS.
3. BASE MATERIAL - LAMINATE AND PREPREG SHALL MEET IPC-4101E/124 or /129
   - TG: MUST BE GREATER THAN OR EQUAL TO 150 DEGREES CELSIUS.
   - TD: MUST BE GREATER THAN OR EQUAL TO 325 DEGREES CELSIUS.
4. COPPER FOIL WEIGHT - SEE STACKUP DETAIL 'A'
   - PCB MANUFACTURER CAN REQUEST AN ALTERNATE STACKUP
   - ALTERNATE STACKUP MUST BE APPROVED IN WRITING BY FOUNDATION DEVICES
5. MINIMUM CONDUCTIVE WIDTH/SPACING TO BE 0.15mm/0.2mm
6. PLATING FINISH: ENIG
7. SOLDERMASK - TO MEET THE REQUIRMENTS OF IPC-SM-840E (OR LATEST REVISION).
   - BLACK COLOR. BOTH SIDES.
   - SOLDERMASK ON SOLDERABLE SURFACES IS PROHIBITED.
   - ALL CIRCUITRY DEFINED AS COVERED SHALL NOT BE EXPOSED.
8. SILKSCREEN - WHITE EPOXY OR ACRYLIC INK. BOTH SIDES. NO SILKSCREEN ON ANY EXPOSED COPPER FEATURE.
9. REMOVE ALL NON-FUNCTIONAL INNER LAYER PADS.
10. ELECTRICAL TEST - 100% IPCD356.
11. DFM CHECK MUST BE RUN ON BOARD DATA BEFORE BUILDING BOARDS.
    - UNLESS PRIOR APPROVAL IS GIVEN IN WRITING BY FOUNDATION.
12. TEARDROPS MAY BE ADDED AT THE FAB HOUSE TO ALL SIGNAL LAYERS.
13. VIA TENTING - ALL VIAS ON BOTH SIDES MUST HAVE TENTING
14. FINISHED PCB THICKNESS IS CRITICAL: FROM L1 PAD TO L4 PAD TO BE 0.8mm +/- 10%
15. TWO SOLDER SAMPLES TO BE PROVIDED
16. SUPPLIER MARKINGS - ON SECONDARY SIDE ONLY.
    - MUST BE UL RECOGNIZED AND MUST HAVE AN ID THAT CONFORMS TO UL94V-0
17. FINISHED PCB MUST BE PANELIZED FOR ASSEMBLY ACCORDING TO CONTRACT MANUFACTURER'S REQUIREMENTS.
    - PANELIZATION MUST BE APPROVED BY CONTRACT MANUFACTURER.

FOUNDATION DEVICES		
PCB PART NUMBER: FD-JL-PCB-MB		
LAYER: DIMENSIONS		
REVISION: C1	VARIANT: [No Variations]	DATE: 11/9/2020



Layer Stack-Up (Detail A)

Layer Name	Gerber Document	Copper Thickness	Insulator Thickness
Top Solder Mask	(.GTS)		
L1 0.5oz Plated Copper Foil	(.GTL)	2.0mil	3.34mil
L2 1.0oz Copper	(.G1)	1.3mil	18.72mil
L3 1.0oz Copper	(.G2)	1.3mil	3.34mil
L4 0.5oz Plated Copper Foil	(.GBL)	2.0mil	
Bottom Solder Mask	(.GBS)		
Total Board Thickness:		32mil	

DRAWN BY M. Beach	FOUNDATION	Foundation Devices Inc. 6 Liberty Square #6018 Boston, MA 02109
CHECKED BY M. Beach	PCB PART NUMBER: FD-JL-PCB-MB	
APPROVED ON 11/09/2020	SIZE C / DATE: 11/9/2020 / VARIANT: [No Variations] / REV C1	
	SCALE: 1/1 / DO NOT SCALE DRAWING / SHEET 1 OF 1	